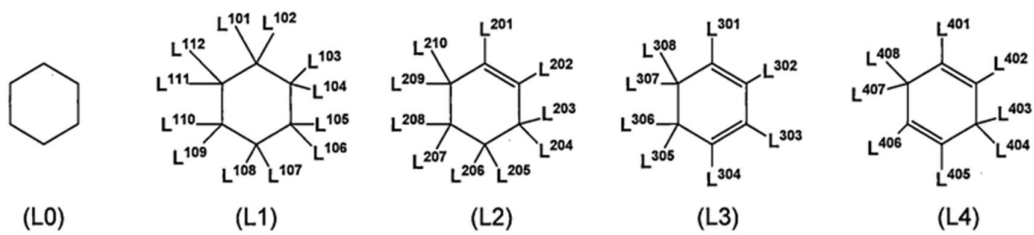


Abstract

The invention provides a semiconductor substrate cleaning method including a step of removing an adhesive layer provided on a semiconductor substrate by use of a remover composition, wherein the remover composition contains a solvent but no salt; and the solvent includes an organic solvent represented by any of formulae (L0) to (L4) (in the formulae, each of L¹⁰¹ to L¹¹² independently represents a hydrogen atom, a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group, and at least one of L¹⁰¹ to L¹¹² represents a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group; each of L²⁰¹ to L²¹⁰ independently represents a hydrogen atom, a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group, and at least one of L²⁰¹ to L²¹⁰ represents a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group; each of L³⁰¹ to L³⁰⁸ independently represents a hydrogen atom, a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group, and at least one of L³⁰¹ to L³⁰⁸ represents a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group; and each of L⁴⁰¹ to L⁴⁰⁸ independently represents a hydrogen atom, a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group, and at least one of L⁴⁰¹ to L⁴⁰⁸ represents a C1 to C5 alkyl group, a C2 to C5 alkenyl group, or a C2 to C5 alkynyl group) in an amount of 80 mass% or more.



[No figure]